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AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

- 1. (Cancelled)
- 2. (Currently Amended) A composition comprising:

the compound of claim 1; and

a compound comprising:

at least one epoxy group;

at least one liquid crystalline disrupting moiety;

a melting point temperature of the compound that is less than 140°C; and

liquid crystallinity of the compound at a temperature greater than 150°C; and

- a filler having a coefficient of thermal expansion that is closer to a coefficient of thermal expansion of silicon than to a coefficient of thermal expansion of an epoxy medium in which the filler is employed that is comparable to that of silicon.
- 3. (Withdrawn) A method comprising:
 contacting a surface of a microelectronic device with the composition of claim 2; and solidifying the composition on the surface.
- 4. (Withdrawn) A microelectronic device comprising:
- a surface; and
- a composition solidified on the surface by the method of claim 3.
- 5. (Currently Amended) The compound of claim [[1]] 2, having the formula:

$$O^{(CH_2)_{n}1}-X^{1}-Ar-X^{2}-(CH_2)_{n}1$$

wherein

Ar includes a liquid crystalline moiety selected from trans-stilbenediyl, triphenyl, 1,4-bis(phenoxycarbonyl)cyclohexdiyl, and diphenyl 1,4-cyclohexane-dicarboxylate;

X¹ and X² independently of one another are selected from oxygen, carbonyl, carboxyl, oxycarbonyl, and amine; and

n¹ and n² independently of one another are numbers selected from 4 to 6.

6. (Currently Amended) The compound of claim [[1]] 2, having the formula:

$$Y^{1}_{O}(CH_{2})_{n}1_{X}1_{Ar}_{X}2_{CH_{2}})_{n}2_{Y}^{2}_{O}$$

wherein

Ar includes a liquid crystalline moiety selected from trans-stilbenediyl, triphenyl, 1,4-bis(phenoxycarbonyl)cyclohexdiyl, diphenyl 1,4-cyclohexanedicaroxylate;

 X^1 and X^2 independently of one another are selected from oxygen, carbonyl, carboxyl, oxycarbonyl, and amine;

Y¹ and Y² independently of one another are selected from oxygen, carbonyl, carboxyl, oxycarbonyl, and amine; and

n¹ and n² independently of one another are numbers selected from 4 to 6.

7. (Currently Amended) The compound of claim [[1]] 2, having the formula:

wherein

X is selected from a C6-10 aryl group and a C5-10 alicyclic group;

each R^1 is independently selected from hydrogen, halogen, and $C_{1:3}$ alkyl optionally substituted with halogen, provided that not more than four of the R^1 are C_2 alkyl optionally substituted with halogen, and provided that not more than three of the R^1 are C_3 alkyl optionally substituted with halogen; and

each R² is independently selected from a C₂₋₆ epoxy.

8. (Currently Amended) The compound of claim [[1]] 2, having the formula:

wherein

X is selected from a C₆₋₁₀ aryl group and a C₅₋₁₀ alicyclic group;

each R^1 is independently selected from hydrogen, halogen, and $C_{1.3}$ alkyl optionally substituted with halogen, provided that not more than four of the R^1 are C_2 alkyl optionally substituted with halogen, and provided that not more than three of the R^1 are C_3 alkyl optionally substituted with halogen;

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each R² is independently selected from a C₂₋₆ epoxy.

- 9. 48. (Cancelled)
- 49. (Previously Presented) The composition of claim 2, wherein the coefficient of thermal expansion of the filler is matched to that of silicon.
- 50. (Previously Presented) The composition of claim 2, wherein the filler comprises one or more selected from silicon particles, silica particles, sand, quartz, silicon dioxide, and clay.
- 51. (Previously Presented) The composition of claim 2, wherein a weight percent of the filler in the composition ranges from 50 to 95 wt%.
- 52. (Previously Presented) The composition of claim 2, wherein the composition comprises an epoxy molding composition.
- 53. (Previously Presented) The composition of claim 2, further comprising: a curing agent; a curing accelerator; and a curing inhibitor.
- 54. (New) The composition of claim 2, wherein the filler comprises silicon.